

REMARKS/ARGUMENTS

Favorable reconsideration of this application as presently amended and in light of the following discussion is respectfully requested.

Claims 1-5, 9-10, 15, 79-85, and 94-98 are presently active; Claims 6-8, 11-14, 16-78 have been previously canceled without prejudice; Claims 86-93 have been presently canceled without prejudice; Claims 1, 15, and 84 are presently amended; and Claims 94-98 have been added. No new matter is added.¹

In the outstanding Office Action, Claims 15, 79, 83-85 were rejected under 35 U.S.C. §102(e) as being anticipated by Yamashita (U.S. Patent 5,875,100); Claims 1, 4, 5 and 9 were rejected under 35 U.S.C. §103(a) as being unpatentable over Mowatt et al. (U.S. Patent 5,306,670) in view of Yamashita; Claims 2 and 3 were rejected under 35 U.S.C. §103(a) as being unpatentable over Mowatt et al. in view of Yamashita, and further in view of Sakaguchi et al. (U.S. Patent 5,837,624); Claims 2-4 and 10 were rejected under 35 U.S.C. §103(a) as being unpatentable over Mowatt et al. in view of Yamashita, and further in view of Ehman et al. (U.S. Patent 6,021,050); Claims 81 and 82 were rejected under 35 U.S.C. §103(a) as being unpatentable over Yamashita in view of Sakaguchi et al.; Claims 80-82 and 86-90 were rejected under 35 U.S.C. §103(a) as being unpatentable over Yamashita in view of Ehman et al.; and Claims 92 and 93 were rejected under 35 U.S.C. §103(a) as being unpatentable over Yamashita in view of Ehman et al., and further in view of Suzuki (U.S. Patent 5,877,550). Claim 91 was indicated as including allowable subject matter.

Firstly, Applicants acknowledge with appreciation the indication that Claim 91 includes allowable subject matter.

¹ Support for the amended claim features and the new claims is found in Applicant's Figures 1-8 and the discussion thereof in the specification.

Secondly, Applicants acknowledge with appreciation the courtesy of Examiner Dinh to discuss this case with Applicant's representatives on September 13, 2007 during which time the issues in the outstanding Office Action were discussed as substantially summarized hereinafter.

Regarding the rejection of the pending claims under, Applicants respectfully submit that the outstanding grounds for rejection have been overcome in light of the discussions with the examiner on September 13, 2007.

Regarding Claim 1, Claim 1 has been amended to define that a core substrate includes a first resin substrate, a second resin substrate having an opening, and a third resin substrate, with the first, second, and third resin substrates disposed in a multilayer manner and to define that the core substrate includes respective interposing bonding plates disposed between the first and second resin substrate and between the second and third resin substrates. Further, Claim 1 clarifies that the first conductive pad formed on the second surface of the first resin substrate facing the chip capacitor is connected to one of the external capacitor electrodes of the chip capacitor *via a first conductive adhesive*. Further, Claim 1 clarifies that the second conductive pad formed on the second surface of the first resin substrate facing the chip capacitor is connected to the other of the external capacitor electrodes of the chip capacitor via a second conductive adhesive.

Applicant submits that these features 1) individually or in combination are not found in the applied references, 2) are similar to the allowable subject matter of original Claim 91, and 3) follow the suggestion made by the examiner during the interview.

Accordingly, independent Claim 1 and the claims dependent therefrom are believed to be allowable.

Regarding Claim 15, Claim 15 has been amended to define that the first resin substrate includes,

at least two conductive pads disposed on a side of the first resin substrate facing the chip capacitor and connected to two electrodes of the chip capacitor

through a conductive adhesive layer respectively, and

an insulating bonding agent disposed between the at least two conductive pads.

This features are shown by way of illustration in Applicant's Figure 1D by conductive pads 36 disposed between insulating bonding agent 33 and in Applicant's Figure 2B which shows the conductive pads 34 and adhesive layer 36 on a side of resin substrate 30a facing chip capacitor 20.

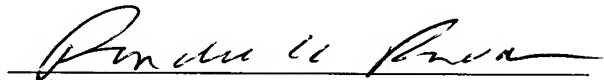
As discussed during the interview, in Yamashita, there is no disclosure or suggestion of 1) insulating layer 30 being disposed between two resins substrates or 2) insulating layer 30 being disposed between to at least two conductive pads. Furthermore, the clarifications here follow the discussions considered during the interview to overcome Yamashita and define subject matter similar to the allowable subject matter of original Claim 91.

Accordingly, independent Claim 15 and the claims dependent therefrom patentably define over Yamashita.

Consequently, in view of the present amendment and in light of the above discussions, the outstanding grounds for rejection are believed to have been overcome. The application as amended herewith is believed to be in condition for formal allowance. An early and favorable action to that effect is respectfully requested.

Respectfully submitted,

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